TOSHIBA Field Effect Transistor Silicon P-Channel MOS Type (Ultra-High-Speed U-MOSIII)

# TPC8116-H

High Efficiency DC/DC Converter Applications
Notebook PC Applications
Portable Equipment Applications
CCFL Inverter Applications

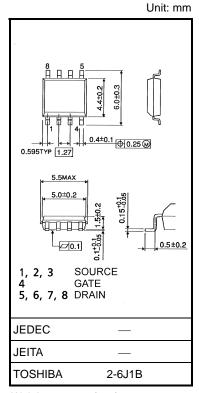
- Small footprint due to a small and thin package
- · High speed switching
- Small gate charge: QSW = 9.7 nC (typ.)
- Low drain-source ON-resistance:  $RDS(ON) = 24m\Omega(typ.)$
- High forward transfer admittance:  $|Y_{fs}| = 14 \text{ S (typ.)}$
- Low leakage current:  $IDSS = -10 \mu A (max) (VDS = -40 V)$
- Enhancement mode:  $V_{th} = -0.8 \text{ to} -2.0 \text{ V (VDS} = -10 \text{ V, ID} = -1 \text{ mA})$

### Maximum Ratings (Ta = 25°C)

Characte	eristic	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	-40	V	
Drain-gate voltage (R	$R_{GS} = 20 \text{ k}\Omega$	$V_{DGR}$	-40	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	-7.5	Α	
Diam current	Pulsed (Note 1)	$I_{DP}$	-30		
Drain power dissipati	on (t = 10 s) (Note 2a)	P <sub>D</sub>	1.9	W	
Drain power dissipati	on (t = 10 s) (Note 2b)	P <sub>D</sub>	1.0	W	
Single-pulse avalance	he energy (Note 3)	E <sub>AS</sub>	26	mJ	
Avalanche current		I <sub>AR</sub>	-7.5	А	
Repetitive avalanche	energy Note 2a) (Note 4)	E <sub>AR</sub>	0.12	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55 to 150	°C	

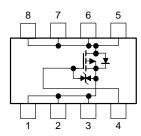
Note: For Notes 1 to 4, refer to the next page.

This transistor is an electrostatic-sensitive device. Handle with care.



Weight: 0.085 g (typ.)

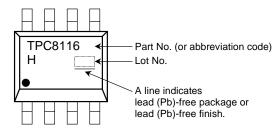
#### **Circuit Configuration**



#### **Thermal Characteristics**

Characteristic	Symbol	Max	Unit	
Thermal resistance, channel to ambient $(t = 10 \text{ s})$ (Note 2a)	R <sub>th (ch-a)</sub>	65.8	°C/W	
Thermal resistance, channel to ambient $(t = 10 \text{ s})$ (Note 2b)	R <sub>th (ch-a)</sub>	125	°C/W	

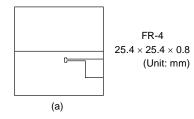
### Marking (Note 5)

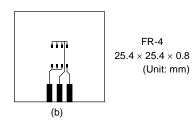


Note 1: The channel temperature should not exceed 150  $^{\circ}$ C during use.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)



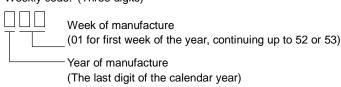


Note 3:  $V_{DD} = -24~V$ ,  $T_{ch} = 25^{\circ}C$  (initial), L = 0.5~mH,  $R_{G} = 25~\Omega$ ,  $I_{AR} = -7.5~A$ 

Note 4: Repetitive rating: pulse width limited by max channel temperature

Note 5: • on the lower left of the marking indicates Pin 1.

\* Weekly code: (Three digits)

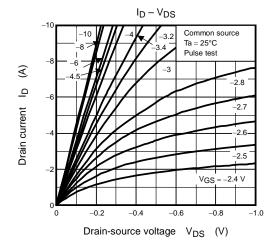


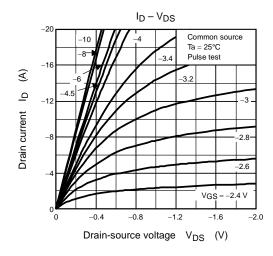
## Electrical Characteristics (Ta = 25°C)

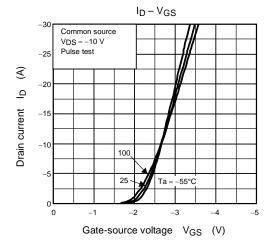
Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cui	rrent	I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_		±10	μА
Drain cutoff curre	ent	I <sub>DSS</sub>	$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-10	μΑ
Drain source bro	rain-source breakdown voltage		$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-40	_	_	V
Diam-source bre	akdowii voltage	V (BR) DSX	$I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$	-     -     -10       -40     -     -       -20     -     -       -0.8     -     -2.0       -     29     37       -     24     30       7     14     -       -     1190     -       -     170     -       -     250     -       -     5     -       -     12     -       -     12     -       -     43     -	v		
Gate threshold v	oltage	V <sub>th</sub>	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$			-2.0	V
Drain-source ON	raciatanaa	P== (0.1)	$V_{GS} = -4.5 \text{ V}, I_D = -3.8 \text{ A}$	_	29	37	mΩ
Diam-source ON	-resistance	R <sub>DS</sub> (ON)	$V_{GS} = -10 \text{ V}, I_D = -3.8 \text{ A}$		30	- 1115.2	
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = -10 \text{ V}, I_{D} = -3.8 \text{ A}$	7	14	_	S
Input capacitance	е	C <sub>iss</sub>		_	1190	_	
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	170	_	pF
Output capacitance		C <sub>oss</sub>		_	250	_	
	Rise time	t <sub>r</sub>	$V_{GS} \stackrel{0\ V}{\longrightarrow} V_{DD} = -3.8\ A$ $V_{GS} \stackrel{0\ V}{\longrightarrow} V_{DUT}$ $V_{DD} \stackrel{\sim}{\longrightarrow} V_{DD} \approx -20\ V$ $V_{DD} \approx -20\ V$ $V_{DD} \approx -20\ V$	_	5	_	- ns
	Turn-on time	t <sub>on</sub>		_	12	_	
Switching time	Fall time	t <sub>f</sub>		_	12	_	
	Turn-off time	t <sub>off</sub>		_	43	_	
Total gate charge		Qg	$V_{DD} \simeq -32 \text{ V}, V_{GS} = -10 \text{V}, I_D = -7.5 \text{A}$	_	27	_	
(gate-source plus	gate-source plus gate-drain)		$V_{DD} \simeq -32$ V, $V_{GS} = -5$ V, $I_D = -7.5$ A	_	15	_	nC
Gate-source charge 1		Q <sub>gs1</sub>	$V_{DD} \simeq -32 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -7.5 \text{A}$	_	3.2	_	
Gate-drain ("Miller") charge		Q <sub>gd</sub>			8.1		
Gate switch char	ge	Q <sub>SW</sub>		_	9.7	_	

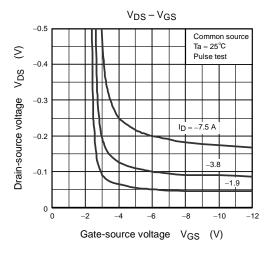
## Source-Drain Ratings and Characteristics (Ta = 25°C)

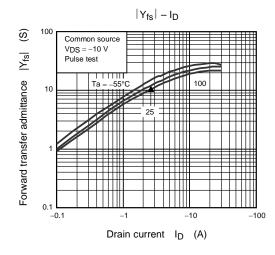
Character	istic		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse	(Note 1)	I <sub>DRP</sub>	_	_	_	-30	Α
Forward voltage (diode)			$V_{DSF}$	$I_{DR} = -7.5 \text{ A}, V_{GS} = 0 \text{ V}$			1.2	V

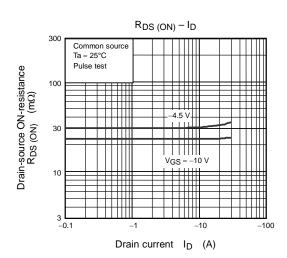


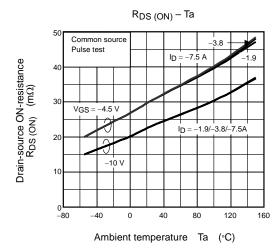


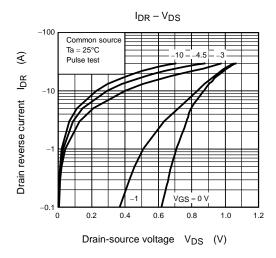


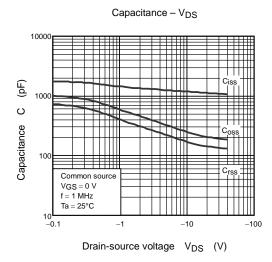


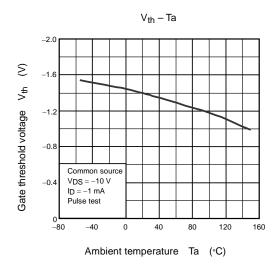


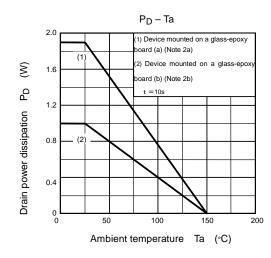


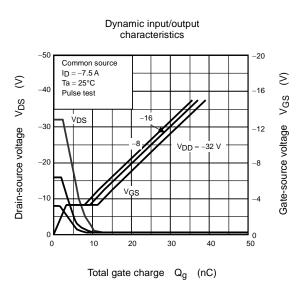


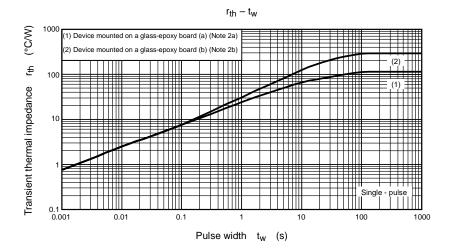


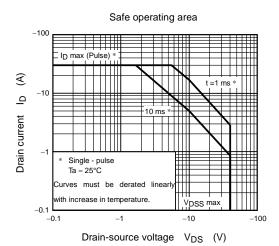












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